

## Full Material Declaration for attached parts list

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 January 2020 [Approved on 6 August 2020, 15:10 GMT]

## Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	11.5%	ALUMINIUM	7429-90-5	1.4%
			Gold	7440-57-5	6.1%
			Silicon	7440-21-3	92.5%
Die attach	Others (Rubber/non-thermoplastic Elastomer)	3.5%	ETHOXYDIGLYCOL ACETATE	112-15-2	2%
			2-Ethyl-2-(((1-oxoallyl)oxy)methyl)-1,3-propanediyl diacrylate	15625-89-5	4%
			Epoxy resin 89	26335-32-0	4%
			Silver	7440-22-4	90%
Encapsulation	EP (Epoxy resin)	47.2%	Carbon black	1333-86-4	0.3%
			Crystallized silicon dioxide	14808-60-7	2.7%
			Epoxy resin 89	26335-32-0	10%
			Quartz sand	60676-86-0	87%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	1.5%	Copper	7440-50-8	100%
Leadfinish	Tin plating	5.3%	Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	31%	iron	14127-53-8	0.1%

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
			Copper	7440-50-8	99.9%

## Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-223	SOT-223	0.04	g